

Appl. No. 10/505,287; Docket No. FR02 0010US
 Amdt. dated November 17, 2006
 Response to Final Office Action dated October 25, 2006

Amendment to the Specification

In the Abstract, please amend as shown.

~~The invention relates to a method of forming electrical connection means on a substrate, which method comprises the following steps:~~

- ~~a) depositing an intermediate layer of material (14) on a substrate (10);~~
- ~~b) forming an etching mask having at least one window;~~
- ~~c) etching the layer of intermediate material in conformity with the mask in order to form at least one aperture therein;~~
- ~~d) coating the lateral side walls of the aperture with a spacer (22) in order to narrow the aperture;~~
- ~~e) depositing at least one conductor material (24) so as to fill the narrowed aperture; and~~
- ~~f) performing an abrasion operation so as to remove excess conductor material outside the aperture.~~

~~The invention is used for the realization of wiring tracks, contact pads and vias.~~

Fig. 6

The present invention is used for the realization of wiring tracks, contact pads, and vias. Consistent with an example embodiment, there is a method of forming electrical connections on a substrate. The method comprises depositing an intermediate layer of material on a substrate. An etching mask having at least one window is formed. The layer of intermediate material is etched in conformity with the mask in order to form at least one aperture therein. In order to narrow the aperture, lateral side-walls of the aperture are coated with a spacer. So as to fill the narrowed aperture, at least one conductor material is deposited therein. So as to remove excess conductor material outside the aperture, an abrasion operation is performed.